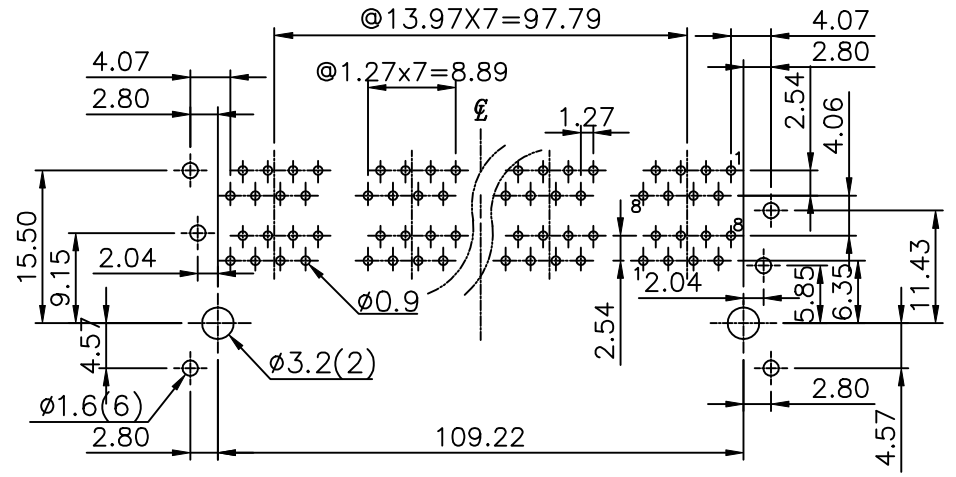
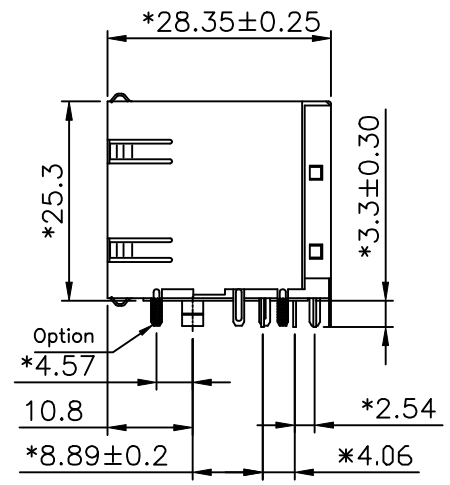
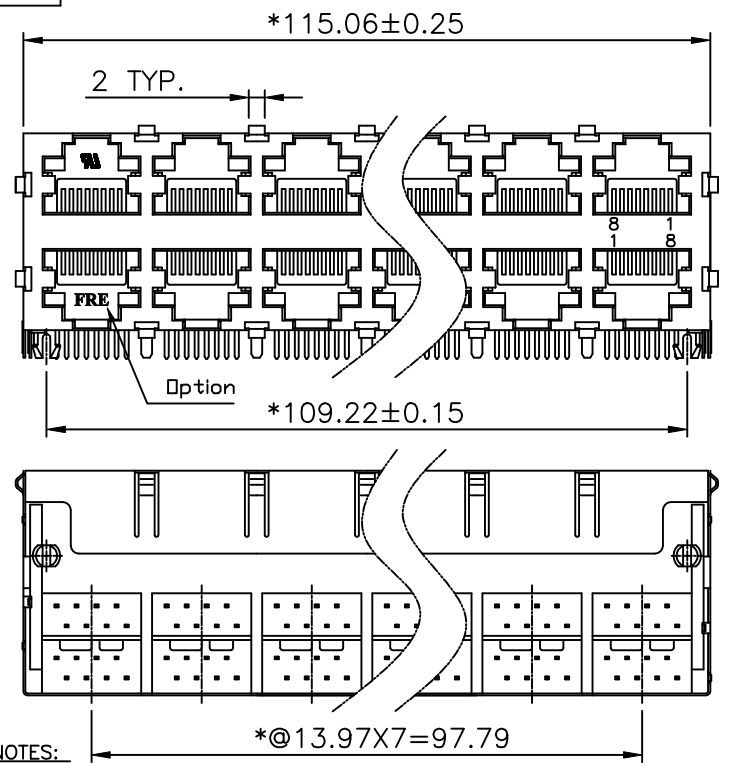


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



PC Board Layout Component Side View  
PC Board Thickness=1.6mm

**NOTES:**  
**ELECTRICAL:**

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 50 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

**MECHANICAL:**

- HOUSING MATERIAL : PBT+30%G.F UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE t=0.35mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

**ENVIRONMENTAL:**

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.
- WAVE SOLDERING TEMPERRATURE: 230°C~250°C(5~10 SECONDS)

MATES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.  
CUL FILE NO. 163191

ROHS PART NUMBER: E5908-XXGXXX-L

- 1-3u" 2-6u" 3-15u" 4-30u" 5-50u"
- 1-W/O TABS
- 2-W/ TOP TABS
- 3-W/ SIDE TABS
- 4-W/ TOP&SIDE TABS
- 5-W/ TOP&BOTTOM&SIDE TABS
- 1-FRONT PEG 4.57
- 4- W/FRE LOGO
- U- W/O FRE LOGO
- 1-FRONT PEG 4.57
- G-FRONT PEG 4.57 W/ 9 GROUNDING TAB
- M-FRONT PEG4.57 FR50
- T- Tin
- N- Nickel
- J- W/NICKEL PLATED WITH TINNED GROUNDING PEG

DETACHED LISTS	MM (INCH)	DFTD JAMY	DATE 8/15/05
	TOLERANCES EXCEPT AS NOTED	CHKD JAMY	DATE 2005/08/18
	MM	MFD	DATE
	.0 ± 0.2	APPV LUSHENO	DATE 2005/08/18
.00 ± 0.15	MATERIAL :		
.000 ± 0.075	ANGLES ± 0.5		
THIRD ANGLE PROJECTION	FINISH:	QT'Y :	
	SCALE : 1.5 : 1	DD NOT SCALE DRAWING	SHEET 1 OF 1

FULL RISE ELECTRONIC CO., LTD			
TITLE STAMPED PIN III			
STACKED GANGED JACK, 2X8			
DRAWING NO. GE593B57-LC		SIZE A3	REV O
/PART NO. SEE NOTE			